


September 20-22, 2006; Prague, Czech Republic
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Track

Distributed Intelligent Control for Flexible Manufacturing

Industrial control is the area with strong theoretical background on the one hand and is subject to the influence of the latest information technologies on the other. These influences create the ever changing palette of requirements and solutions. Moreover, the market requirements for higher production flexibility on the one hand and higher reliability and safety on the other add new dimension of complexity and raise new frontiers of challenges both for the theory and for the engineering solutions. The track is dedicated to presentation of the works reflecting these challenges. The contributions are encouraged on particular areas and technologies listed below as well as on synergy and emerging trends. The track focuses on the following issues (but is not limited to):

Design methodologies and design patterns for re-configurable manufacturing and process systems:

- Integration of different aspects of automation: control, supervision, human operation, diagnostics, visualization, etc.;
- Design and implementation of distributed control systems
- Recent developments in standardization
- Test cases, benchmarks
- Applications and experiences in practice:
- Batch process control
- Hybrid systems and models

Formal models of manufacturing and process systems:

- Modular and incremental approaches in modelling
- Tools
- Logic programming and verification of control systems;
- Synthesis methods for flexible logic control;
- New applications of discrete event simulation;
- Supervisory control: Theory development and Practical Applications;
- Model-based automation system engineering

+ a Special Session is planned "The IEC 61499 Function Block Model in Factory Automation"

Description is available at: http://seq.ee.upatras.gr/thrambo/dev/ETFA-06_SS01_cfp.pdf

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Solicited Papers: Research papers; reporting on new developments in technological sciences. Industry and development papers; reporting on actual developments of technology, products, systems, and solutions. Tutorial and survey papers.

Special sessions. Proposal for special sessions are solicited. A proposal should include title of the session, organizers, list of titles of papers/names of authors/contact addresses. The organizers are responsible for the review process and enforcing the quality.

Submission of Papers: The working language of the conference is English. Two types of submissions are solicited. Long Papers – limited to 8 double column pages in a font no smaller than 10-points. Work-in-Progress and Industry practice – limited to 4 double column pages in a font no smaller than 10-points. Manuscripts must be submitted electronically in PDF format, according to the instructions contained in the Conference web site. Prospective authors are invited to visit the conference web site at the following URL:

www.action-m.com/etfa2006

Further Information: ETFA'06 Conference Secretariat: Czech Technical University in Prague, Zikova 4, 166 36 Prague 6, Czech Republic, Tel: +420-221500201, Email: etfa@labe.felk.cvut.cz, or Ms. Milena Zeithamlova Email: milena@action-m.com

Paper Acceptance: Each accepted paper must be presented at the conference by one of the authors. The final manuscript must be accompanied by a registration form and a registration fee payment proof. All conference attendees, including authors and session chairpersons, must pay the conference registration fee, and their travel expenses.

Author's Schedule:

Deadline for submission of long papers:

March 31, 2006

Notification of acceptance of long papers:

May 25, 2006

Deadline for submission of work-in-progress papers and Industry practice:

June 1, 2006

Notification of acceptance of work-in-progress papers and Industry practice:

July 1, 2006

Deadline for submission of final manuscripts:

July 1, 2006